20W, 3GHz General Purpose RF LDMOS FETs

Description

The MM2002A is a 20-watt, highly rugged, unmatched LDMOS FET, designed for wideband commercial and industrial applications at frequencies up to 3 GHz. It can be used in Class AB/B and Class C for all typical modulation formats. It can support CW, pulsed CW either saturated or linear operation.

• Typical Performance (On Innogration fixture with device soldered):

V _{DD} = 28 Volts, I _{DQ} =	= 50 mA,	CW.
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Freq	P1dB	P1dB	P1dB	P1dB	P3dB	P3dB	P3dB
(MHz)	(dBm)	(W)	Eff(%)	Gain(dB)	(dBm)	(W)	Eff(%)
2800	45.63	36.5	49.6	10.86	46.42	43.9	51.7
2850	45.02	31.8	51.5	11.65	45.83	38.3	53.6
2900	44.05	25.4	49.4	11.6	44.89	30.8	51.8

Features

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Excellent thermal stability, low HCI drift
- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Pb-free, RoHS-compliant

Suitable Applications

- General purpose power amplifier
- L, S band power amplifier

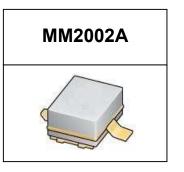
Table 1. Maximum Ratings

Rating	Symbol	Value	Unit			
DrainSource Voltage	V _{DSS}	+65	Vdc			
GateSource Voltage	V _{GS}	-10 to +10	Vdc			
Operating Voltage	V _{DD}	+32	Vdc			
Storage Temperature Range	Tstg	-65 to +150	°C			
Case Operating Temperature	Tc	+150	°C			
Operating Junction Temperature	TJ	+225	°C			
Fable 2. Thermal Characteristics						
Characteristic	Symbol	Value	Unit			

Onaracionstic	Gymbol	Value					
Thermal Resistance, Junction to Case	Rejc	1.6	°C/W				
T_c = 85°C, T_J =200°C, DC test	RejC	1.0	C/VV				
Table 3 ESD Protection Characteristics							

Table 3. ESD Protection Characteristics

Test Methodology	Class
Human Body Model (per JESD22A114)	Class 2

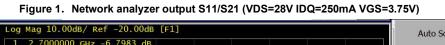


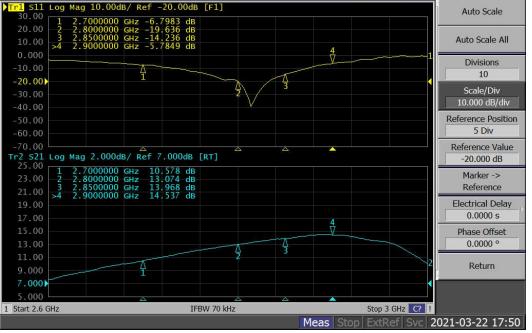
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Table 4. Electrical Characteristics (TA = 25 °C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit	
OC Characteristics						
Drain-Source Voltage	N	65	70		V	
V _{GS} =0, I _{DS} =500uA	V _{(BR)DSS}	60	70		v	
Zero Gate Voltage Drain Leakage Current				1		
(V _{DS} = 50V, V _{GS} = 0 V)	DSS				μA	
Zero Gate Voltage Drain Leakage Current				1		
(V _{DS} = 28 V, V _{GS} = 0 V)	DSS			1	μΑ	
GateSource Leakage Current				1	•	
$(V_{GS} = 9 V, V_{DS} = 0 V)$	I _{GSS}				μA	
Gate Threshold Voltage	M (m)		1.98		V	
$(V_{DS} = 28V, I_{D} = 600 \ \mu A)$	$V_{GS}(th)$				v	
Gate Quiescent Voltage	N		2.53		V	
(V_{DD} = 28 V, I_D = 50 mA, Measured in Functional Test)	V _{GS(Q)}		2.55		V	
Common Source Input Capacitance			23.5		۳Ľ	
(V _{GS} = 0V, V _{DS} =28 V, f = 1 MHz)	C _{ISS}		23.5		pF	
Common Source Output Capacitance			0.7			
(V _{GS} = 0V, V _{DS} =28 V, f = 1 MHz)	Coss		9.7		pF	
Common Source Feedback Capacitance						
(V _{GS} = 0V, V _{DS} =28 V, f = 1 MHz)	C _{RSS}		0.7		pF	
.oad Mismatch (In Innogration Test Fixture, 50 ohm system): $$ $$ $$	$V_{\text{DD}} = 28 \text{ Vdc}, \text{ I}_{\text{DQ}} = 3$	50 mA, f = 290	0 MHz			
VSWR 10:1 at 20W pulse CW Output Power	No Device D	egradation				

TYPICAL CHARACTERISTICS





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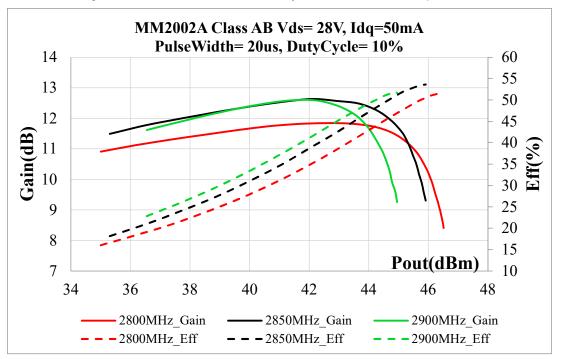
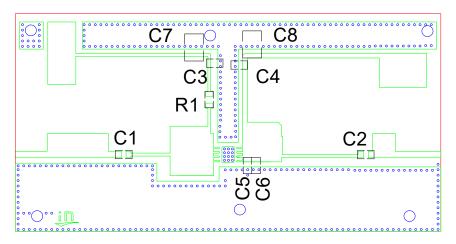
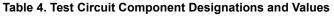


Figure 2. Power Gain and Drain Efficiency as Function of Pulse Output Power

Figure 3. Test Circuit Component Layout (PCB: 20 Mils, RO4350B)

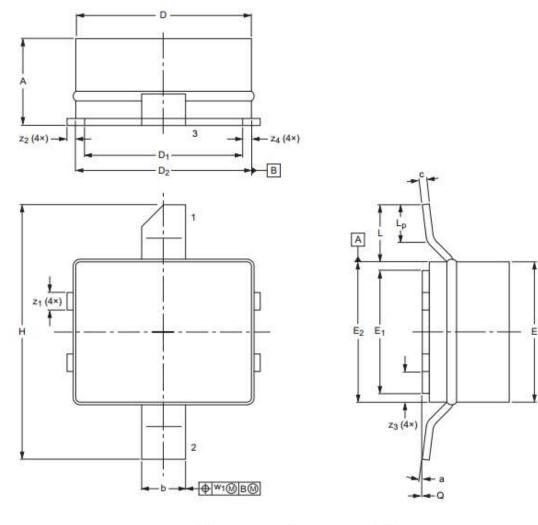




Designator	Comment	Footprint	Quantity
C1	3.9pF	0603	1
C2, C3, C4	8.2pF	0603	3
C5	0.5pF	0603	1
C6	0.3pF	0603	1
C7, C8	10uF/100V	1210	2
R1	10ohm	0603	1

Package Outline

Earless Flanged ceramic package; 2 leads(1-Drain,2-Gate,3-Source)



0 2.5 5 mm scale

UNIT	A	b	с	D	D1	Е	E1	E ₂	н	L	L _P	Q	W1	Z 1	Z 2	Z 3	Z 4	α
	2.34	1.35	0.23	5.16	4.65	4.14	3.63	4.14	7.49	2.03	1.02	0.1	0.05	0.58	0.25	0.97	0.51	7°
mm	2.13	1.19	0.18	5.00	4.50	3.99	3.48	3.99	7.24	1.27	0.51	0.0	0.25	0.43	0.18	0.81	0.00	0°

OUTLINE		REFERENCE	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	JEITA	PROJECTION	ICCCL DATE
PKG-MM					18/6/2014

Revision history

Table 5. Document revision history

Revision	Datasheet Status
Rev 1.0	Product Datasheet

Application data based on LSM-21-07

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